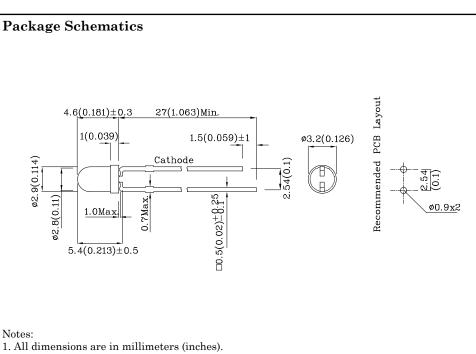


## Features

- Radial / Through hole package
- $\bullet$  Reliable & robust
- Low power consumption
- Available on tape and reel
- RoHS Compliant





2. Tolerance is  $\pm 0.25(0.01")$  unless otherwise noted.

3. Specifications are subject to change without notice.

Absolute Maximum Ratings (T <sub>A</sub> =25°C)		Red (GaAsP/GaP)	Unit		
Reverse Voltage	$V_{R}$	5	V		
Forward Current	$I_{\rm F}$	30	mA		
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	ifs	160	mA		
Power Dissipation	PD	75	mW		
Operating Temperature	$T_{\rm A}$	-40 ~ +85	°C		
Storage Temperature	Tstg	-40 ~ +85			
Lead Solder Temperature [2mm Below Package Base]	260°C For 3 Seconds				
Lead Solder Temperature [5mm Below Package Base]	260°C For 5 Seconds				

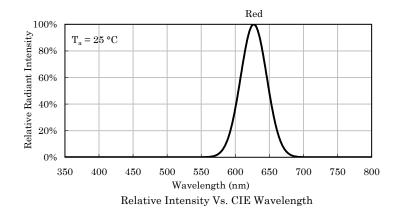
A Relative Humidity between 40% and 60% is recommended in ESD-protected work areas to reduce static build up during assembly process (Reference JEDEC/JESD625-A and JEDEC/J-STD-033)

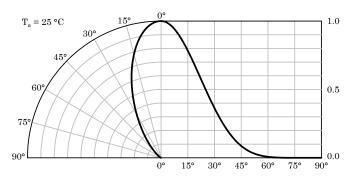
Operating Characteristics (T <sub>A</sub> =25°C)		Red (GaAsP/GaP)	Unit
Forward Voltage (Typ.) (I <sub>F</sub> =10mA)	$V_{\rm F}$	1.9	V
Forward Voltage (Max.) (I <sub>F</sub> =10mA)	$V_{\mathrm{F}}$	2.3	V
Reverse Current (Max.) (V <sub>R</sub> =5V)	$I_R$	10	uA
Wavelength of Peak Emission CIE127-2007*(Typ.) (I <sub>F</sub> =10mA)	λP	627*	nm
Wavelength of Dominant Emission CIE127-2007*(Typ.) (I <sub>F</sub> =10mA)	λD	617*	nm
Spectral Line Full Width At Half-Maximum (Typ.) (I <sub>F</sub> =10mA)	$ riangle\lambda$	45	nm
Capacitance (Typ.) (V <sub>F</sub> =0V, f=1MHz)	С	15	pF

Part Number	Emitting Color	Emitting Material	Lens-color	Luminous Intensity CIE127-2007* (I <sub>F</sub> =10mA) mcd		Wavelength CIE127-2007* nm λP	Viewing Angle 20 1/2
				min.	typ.		
XLUR11D	Red	GaAsP/GaP	Red Diffused	12 10*	29 19*	627*	50°

\*Luminous intensity value and wavelength are in accordance with CIE127-2007 standards.

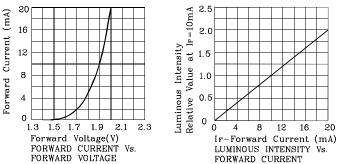


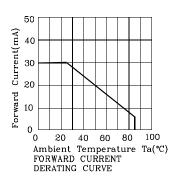


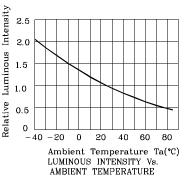


Spatial Distribution

Red

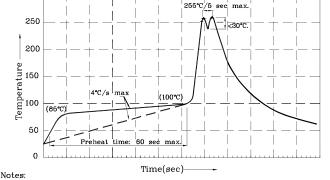






(°C)300

Wave Soldering Profile For Thru-Hole Products (Pb-Free Components)



I.Recommend pre-heat temperature of 105°C or less (as measured with a thermocouple attached to the LED pins) prior to immersion in the solder wave with a maximum solder bath temperature of 260°C
2.Peak wave soldering temperature between 245°C ~ 255°C for 3 sec

(5 sec max).

3.Do not apply stress to the epoxy resin while the temperature is above  $85^{\circ}$ C. 4.Fixtures should not incur stress on the component when mounting and

during soldering process. 5.SAC 305 solder alloy is recommended.

6.No more than one wave soldering pass

### Remarks:

If special sorting is required (e.g. binning based on forward voltage, luminous intensity / luminous flux, or wavelength),

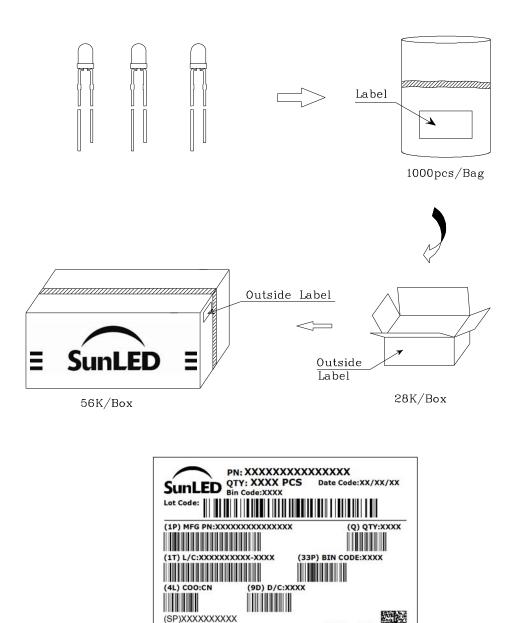
the typical accuracy of the sorting process is as follows:

- 1. Wavelength: +/-1nm
- 2. Luminous Intensity / Luminous Flux: +/-15%
- 3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.



# PACKING & LABEL SPECIFICATIONS



RoHS Complia Made in China

### TERMS OF USE

- 1. Data presented in this document reflect statistical figures and should be treated as technical reference only.
- 2. Contents within this document are subject to improvement and enhancement changes without notice.
- 3. The product(s) in this document are designed to be operated within the electrical and environmental specifications indicated on the datasheet.
- User accepts full risk and responsibility when operating the product(s) beyond their intended specifications. 4. The product(s) described in this document are intended for electronic applications in which a person's life is not reliant upon the LED. Please
- consult with a SunLED representative for special applications where the LED may have a direct impact on a person's life.
- 5. The contents within this document may not be altered without prior consent by SunLED.
- $6. \ Additional \ technical \ notes \ are \ available \ at \ \underline{https://www.SunLEDusa.com/TechnicalNotes.asp}$